# APPENDIX III: Notification Form

In accordance with the 40 CFR 761.61(c) risk-based disposal approval issued by the U.S. EPA to dispose of PCB Remediation Wastes generated at secure utility assets and containing as-found concentrations < 50 ppm PCBs, the following information is provided:

**A. USWAG MEMBER IDENTIFICATION**:

Company Name (as it appears in the Approval)    Ameren Illinois

Address including City, County, State, Zip    6 Richard Mark Way, Collinsville, Madison County, Illinois , 62234

Primary USWAG Member Contact Name    H.E. Chamblin

Primary USWAG Member Contact Information
(phone and email address)    217/424-6592, hchamblin@ameren.com

Primary Recordkeeping Contact Name (if not the
same as the Primary USWAG Member Contact)

Primary Recordkeeping Contact Information
(phone, email address, and address if not the
same as the addresses listed above)

**B. SITE LOCATION:**

EPA ID Number of the Secured Asset (if
available)

Address including City, County, State, Zip    S. B St. & W. 5th Ave, Monmouth, Warren County, Illinois, 61462

Latitude/Longitude (if no street address)

Primary Recordkeeping Contact Name (if not the
same as the Primary USWAG Member Contact)

Primary Recordkeeping Contact Information
(phone, email address, and address if not the
same as the addresses listed above)

**C. WASTE**

Date waste was discovered    08/29/2023

Description of waste (max concentration, media,
estimated quantity)    Electric Substation Soil and Rock, 8 ppm PCB, approximately 4 CY

Size of Site area containing the PCB Remediation
Waste being disposed of    Approximate 10' X 10' area

Name, location, and type of facility at which the
waste will be disposed of    Waste Management's Milam Landfill, 601 Madison Rd., E. St. Louis, IL., MSW landfill

**D. SUBMITTAL**

Method of Submittal of this Notification (i.e.,
Certified Mail or Email)    Email

Date Submitted    11/02/2023

Submitted to (print name)   mooney.charlotte@epa.gov, ORCRPCBS@epa.gov, ramanauskas.peter@epa.gov, paul.eisenbrandt@illinois.gov

Submitted by (print name)   H.E. Chamblin

Submitted by (signature)